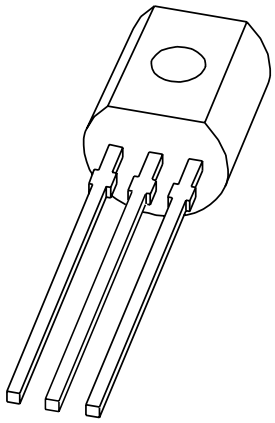
DATA SHEET



BC556; BC557
PNP general purpose transistors

Product data sheet
Supersedes data of 1999 Apr 15

2004 Oct 11

PNP general purpose transistors BC556; BC557

FEATURES

- Low current (max. 100 mA)
- Low voltage (max. 65 V).

APPLICATIONS

- General purpose switching and amplification.

DESCRIPTION

PNP transistor in a TO-92; SOT54 plastic package.
NPN complements: BC546 and BC547.

PINNING

PIN	DESCRIPTION
1	emitter
2	base
3	collector

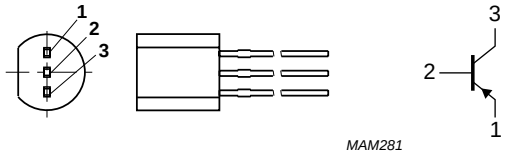


Fig.1 Simplified outline (TO-92; SOT54) and symbol.

ORDERING INFORMATION

TYPE NUMBER	PACKAGE		
	NAME	DESCRIPTION	VERSION
BC556	SC-43A	plastic single-ended leaded (through hole) package; 3 leads	SOT54
BC557			

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V_{CBO}	collector-base voltage	open emitter			
	BC556		–	–80	V
	BC557		–	–50	V
V_{CEO}	collector-emitter voltage	open base			
	BC556		–	–65	V
	BC557		–	–45	V
V_{EBO}	emitter-base voltage	open collector	–	–5	V
I_C	collector current (DC)		–	–100	mA
I_{CM}	peak collector current		–	–200	mA
I_{BM}	peak base current		–	–200	mA
P_{tot}	total power dissipation	$T_{amb} \leq 25$ °C	–	500	mW
T_{stg}	storage temperature		–65	+150	°C
T_j	junction temperature		–	150	°C
T_{amb}	ambient temperature		–65	+150	°C

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
$R_{th(j-a)}$	thermal resistance from junction to ambient	note 1	250	K/W

Note

1. Transistor mounted on an FR4 printed-circuit board.

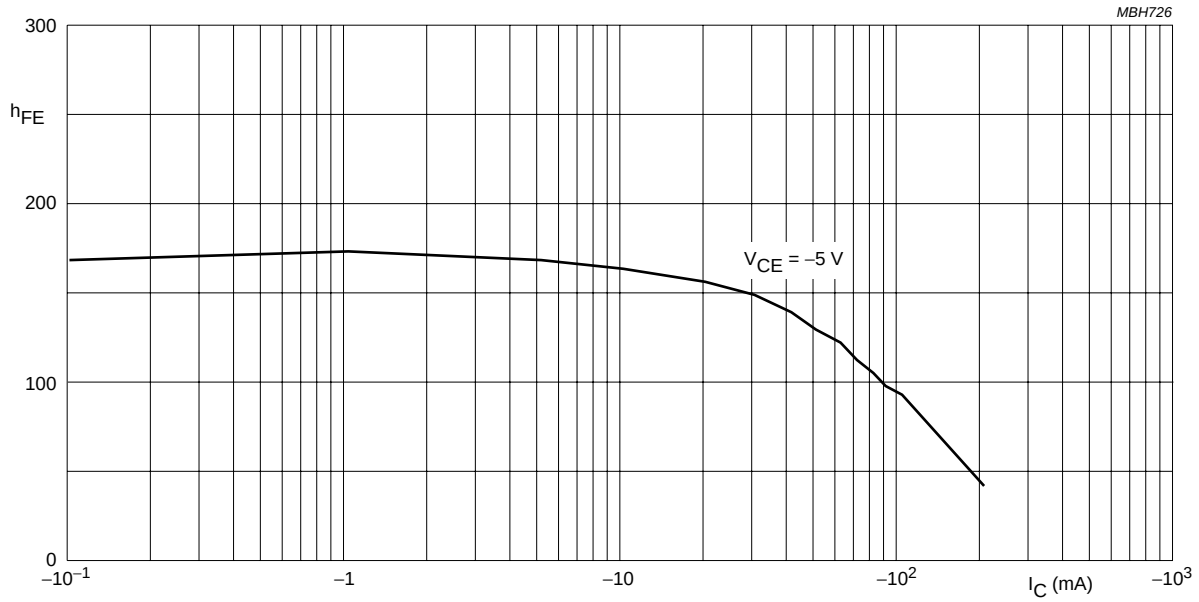
CHARACTERISTICS

T_{amb} = 25 °C unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I_{CBO}	collector-base cut-off current	V_{CB} = –30 V; I_E = 0 A	–	–1	–15	nA
		V_{CB} = –30 V; I_E = 0 A; T_j = 150 °C	–	–	–4	μA
I_{EBO}	emitter-base cut-off current	V_{EB} = –5 V; I_C = 0 V	–	–	–100	nA
h_{FE}	DC current gain	I_C = –2 mA; V_{CE} = –5 V; see Figs 2, 3 and 4				
	BC556		125	–	475	
	BC557		125	–	800	
	BC556A		125	–	250	
	BC556B; BC557B		220	–	475	
	BC557C		420	–	800	
V_{CEsat}	collector-emitter saturation voltage	I_C = –10 mA; I_B = –0.5 mA	–	–60	–300	mV
		I_C = –100 mA; I_B = –5 mA	–	–180	–650	mV
V_{BEsat}	base-emitter saturation voltage	I_C = –10 mA; I_B = –0.5 mA; note 1	–	–750	–	mV
		I_C = –100 mA; I_B = –5 mA; note 1	–	–930	–	mV
V_{BE}	base-emitter voltage	V_{CE} = –5 V; I_C = –2 mA; note 2	–600	–650	–750	mV
		V_{CE} = –5 V; I_C = –10 mA; note 2	–	–	–820	mV
C_c	collector capacitance	V_{CB} = –10 V; I_E = i_e = 0 A; f = 1 MHz	–	3	–	pF
C_e	emitter capacitance	V_{EB} = –0.5 V; I_C = i_c = 0 A; f = 1 MHz	–	10	–	pF
f_T	transition frequency	V_{CE} = –5 V; I_C = –10 mA; f = 100 MHz	100	–	–	MHz
F	noise figure	V_{CE} = –5 V; I_C = –200 μA; R_S = 2 kΩ; f = 1 kHz; B = 200 Hz	–	2	10	dB

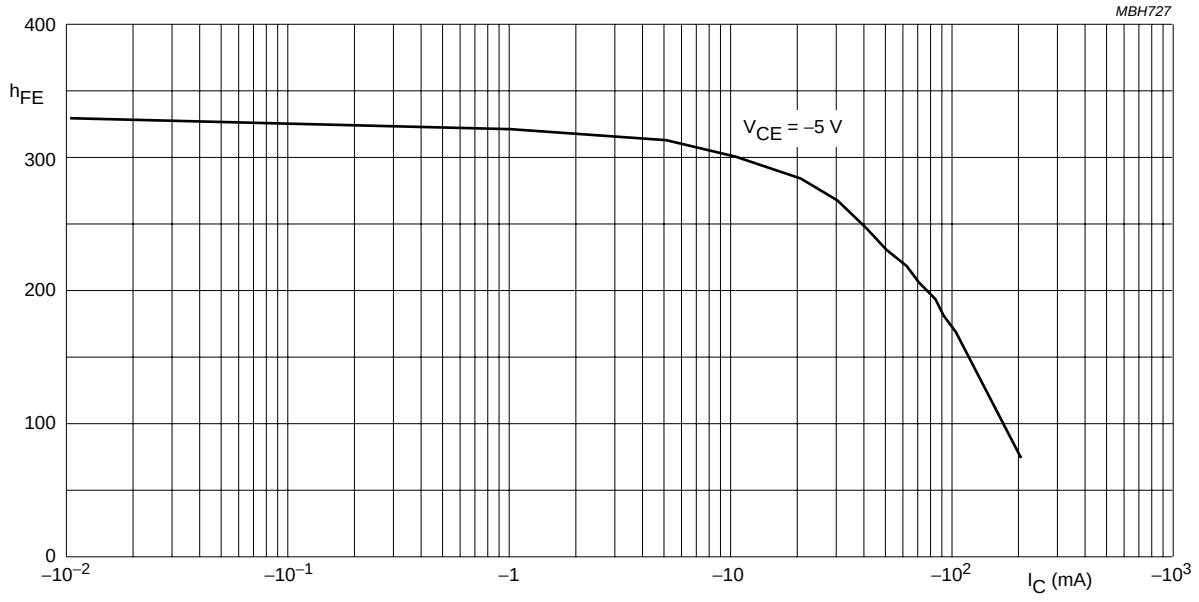
Notes

1. V_{BEsat} decreases by about –1.7 mV/K with increasing temperature.
2. V_{BE} decreases by about –2 mV/K with increasing temperature.



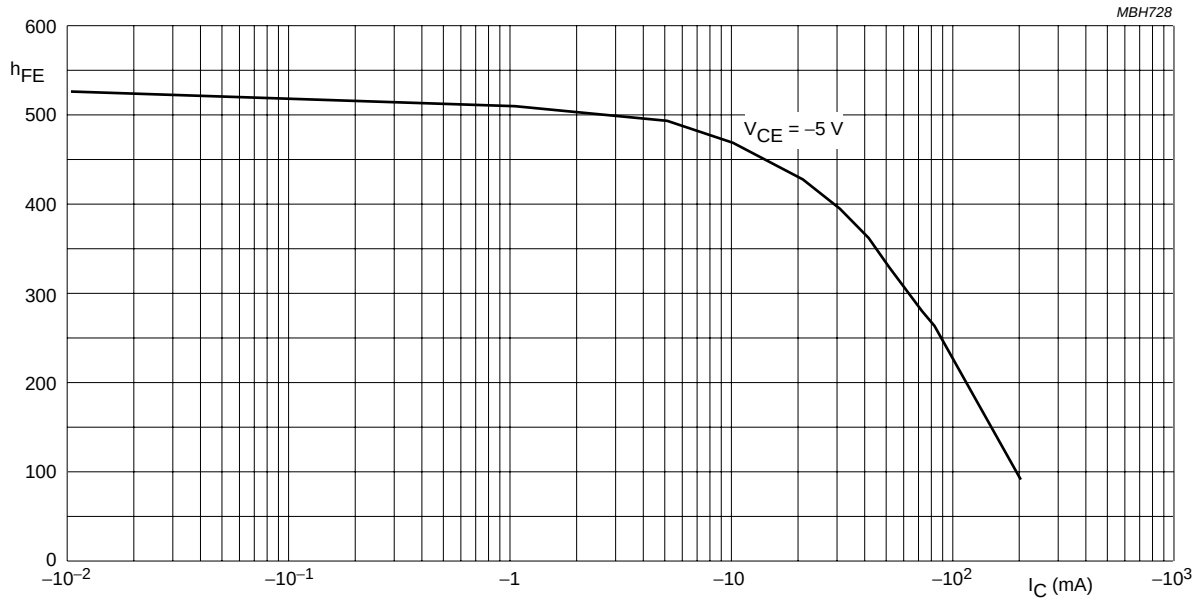
BC556A.

Fig.2 DC current gain; typical values.



BC556B; BC557B.

Fig.3 DC current gain; typical values.

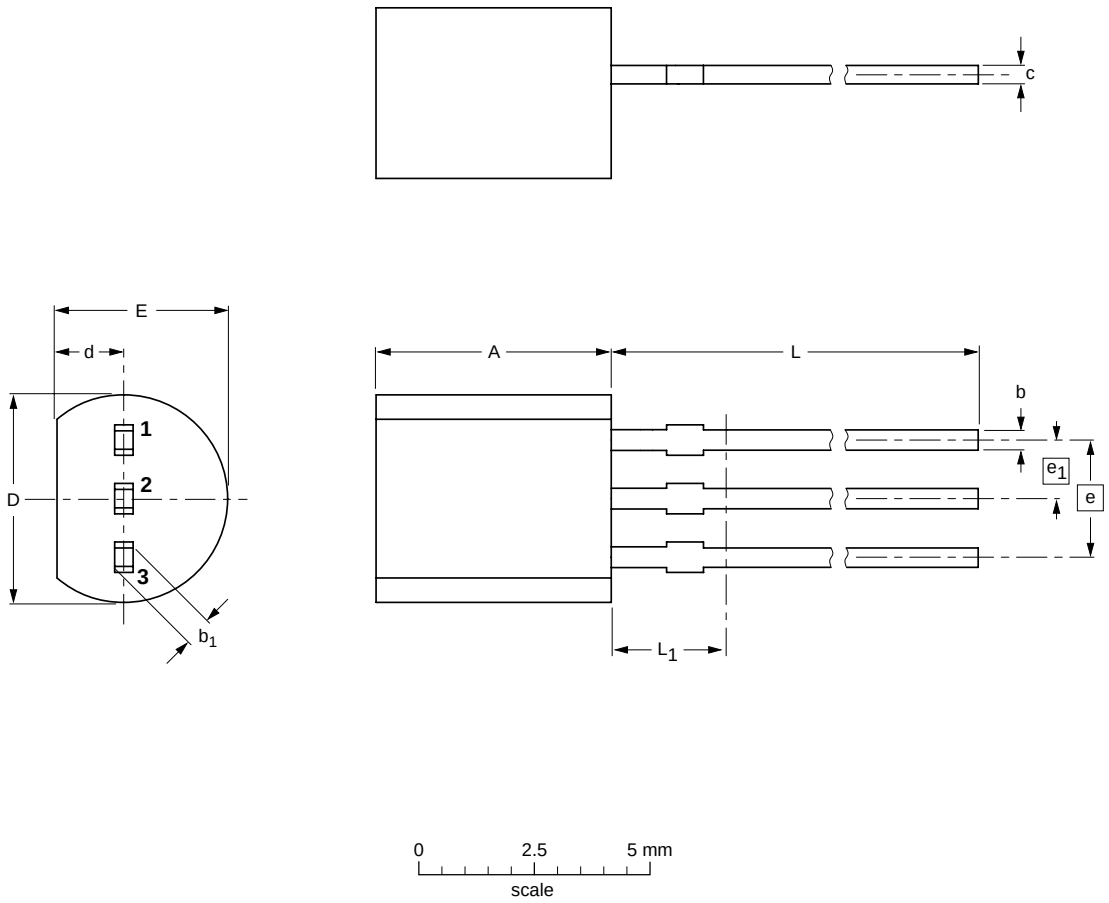


BC557C.

Fig.4 DC current gain; typical values.

PACKAGE OUTLINE

Plastic single-ended leaded (through hole) package; 3 leads **SOT54**



DIMENSIONS (mm are the original dimensions)

UNIT	A	b	b_1	c	D	d	E	e	e_1	L	L_1 (1) max.
mm	5.2 5.0	0.48 0.40	0.66 0.55	0.45 0.38	4.8 4.4	1.7 1.4	4.2 3.6	2.54	1.27	14.5 12.7	2.5

Note

1. Terminal dimensions within this zone are uncontrolled to allow for flow of plastic and terminal irregularities.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT54		TO-92	SC-43A			~~04-06-28~~ 04-11-16

DATA SHEET STATUS

DOCUMENT STATUS[1]	PRODUCT STATUS[2]	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

Notes

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NXP Semiconductors

Customer notification

This data sheet was changed to reflect the new company name NXP Semiconductors, including new legal definitions and disclaimers. No changes were made to the technical content, except for package outline drawings which were updated to the latest version.

Contact information

For additional information please visit: **http://www.nxp.com**
For sales offices addresses send e-mail to: **salesaddresses@nxp.com**

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